



NOTES :

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. EXTRA PIN(D4) TO BE FLOATING FROM ANY PINS.
6. LEAD RESISTANCE : 800mΩMAX.

CATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	S-0
						121 PIN GRID ARRAY PACKAGE	UNLESS OTHERWISE SPECIFIED	S.N	S.A		D-0
						SCALE	1:005				DATE
						MATERIAL					FEB.14.'90

PB121Y112-1

WIRE BOND PAD / CONNECTOR PIN INTERCONNECTION PLAN

W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.
1	C 3	21	J 1	41	N 5	61	L11	81	E13	101	A 9		
2	B 2	22	J 2	42	L 6	62	M12	82	E12	102	C 8		
3	B 1	23	K 1	43	M 6	63	M13	83	D13	103	B 8		
4	D 3	24	J 3	44	N 6	64	K11	84	E11	104	A 8		
5	C 2	25	K 2	45	M 7	65	L12	85	D12	105	B 7		
6	C 1	26	L 1	46	L 7	66	L13	86	C13	106	C 7		
7	D 2	27	M 1	47	N 7	67	K12	87	B13	107	A 7		
8	E 3	28	K 3	48	N 8	68	J11	88	D11	108	A 6		
9	D 1	29	L 2	49	M 8	69	K13	89	C12	109	B 6		
10	E 2	30	N 1	50	L 8	70	J12	90	A13	110	C 6		
11	E 1	31	L 3	51	N 9	71	J13	91	C11	111	A 5		
12	F 3	32	M 2	52	M 9	72	H11	92	B12	112	B 5		
13	F 2	33	N 2	53	N10	73	H12	93	A12	113	A 4		
14	F 1	34	L 4	54	L 9	74	H13	94	C10	114	C 5		
15	G 2	35	M 3	55	M10	75	G12	95	B11	115	B 4		
16	G 3	36	N 3	56	N11	76	G11	96	A11	116	A 3		
17	G 1	37	M 4	57	N12	77	G13	97	B10	117	A 2		
18	H 1	38	L 5	58	L10	78	F13	98	C 9	118	C 4		
19	H 2	39	N 4	59	M11	79	F12	99	A10	119	B 3		
20	H 3	40	M 5	60	N13	80	F11	100	B 9	120	A 1		

S/R	N C
D/A	N C
EXTRA PIN	N C

ATTN						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						121 PIN GRID ARRAY PACKAGE	UNLESS OTHERWISE SPECIFIED	S.N	S.A		FEB. 14 '99
						SCALE	MATERIAL				

